



### ■ Pin Descriptions

Pin No.	Symbol	Description	Pin No.	Symbol	Description
1	VM12	Channel 1, 2 power supply	17	FB3	Channel 3 feedback signal output pin
2	FO1	Channel 1 forward output pin	18	CT	Triangular wave output pin
3	RO1	Channel 1 reverse output pin	19	CLK	CLK synchronous pulse input pin
4	SO1	Channel 1 feedback signal input pin	20	VPUMP	Charge pump step-up voltage output
5	YC1A	Channel 1 feedback gain adjustment pin A	21	BC2	Charge pump capacitor connection pin 2
6	YC1B	Channel 1 feedback gain adjustment pin B	22	BC1	Charge pump capacitor connection pin 1
7	YC2A	Channel 2 feedback gain adjustment pin A	23	N.C.	N.C.
8	YC2B	Channel 2 feedback gain adjustment pin B	24	RO3	Channel 3 reverse output pin
9	FB1	Channel 1 feedback signal output pin	25	VM3	Channel 3 power supply
10	In1	Channel 1 driver input pin	26	PG3	Channel 3 power ground
11	FB2	Channel 2 feedback signal output pin	27	FO3	Channel 3 forward output pin
12	In2	Channel 2 driver input pin	28	SB	All shut off input pin
13	V <sub>REF</sub>	Reference voltage input pin	29	SO2	Channel 2 feedback signal input pin
14	SGND	Control circuit ground	30	RO2	Channel 2 reverse output pin
15	In3	Channel 3 driver input pin	31	FO2	Channel 2 forward output pin
16	SV <sub>DD</sub>	Control circuit power supply	32	PG12	Channel 1, 2 power supply

### ■ Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage <sup>*2</sup>	SV <sub>DD</sub>	6.0	V
	V <sub>M12</sub> , V <sub>M3</sub>		
Supply voltage application range	SV <sub>DD</sub>	-0.3 to +6.0	V
	V <sub>M12</sub> , V <sub>M3</sub>		
Drive output voltage <sup>*7</sup>	V <sub>(m)</sub>	7.0	V
Control signal input voltage <sup>*8</sup>	V <sub>(n)</sub>	SGND to SV <sub>DD</sub>	V
Supply current <sup>*3</sup>	I <sub>SVDD</sub>	200	mA
	I <sub>VM12</sub>	2 000	
	I <sub>VM3</sub>	1 200	
Drive output current channel 1, 2 <sup>*5</sup>	I <sub>(o)</sub>	±1 000	mA
Drive output current channel 3 <sup>*6</sup>	I <sub>(p)</sub>	±1 200	mA
Power dissipation <sup>*4</sup>	P <sub>D</sub>	400	mW
Operating ambient temperature <sup>*1</sup>	T <sub>opr</sub>	-30 to +75	°C
Storage temperature <sup>*1</sup>	T <sub>stg</sub>	-55 to +150	°C

Note) Do not apply external currents or voltages to any pins not specifically mentioned expect for the power supply and GND pins.

For circuit currents, '+' denotes current flowing into the IC, and '-' denotes current flowing out of the IC.

\*1: Except for the operating ambient temperature and storage temperature, all ratings are for T<sub>a</sub> = 25°C.

\*2: The voltage in a step-up voltage circuit exceeds a supply voltage. Refer to "■ Electrical Characteristics" for an allowable value of a step-up voltage.

\*3: Use within 1 000 mA in each channel 1 and channel 2.

### ■ Absolute Maximum Ratings (continued)

Note) \*4: Use within the range of not exceeding  $P_D = 400$  mW without heat sink and at  $T_a = 75^\circ\text{C}$  in accordance with an allowable power dissipation characteristic curve of "■ Application Note".

\*5: o = 2, 3, 30, 31

\*6: p = 24, 27

\*7: m = 2, 3, 4, 24, 27, 29, 30, 31

\*8: n = 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 15, 17, 18, 19, 22, 28

### ■ Recommended Operating Range

Parameter	Symbol	Range	Unit
Supply voltage	$V_{DD}$	4.5 to 5.0 to 5.5	V
	$V_{M12}$ , $V_{M3}$	3.5 to 5.0 to 5.5	

### ■ Electrical Characteristics at $V_{DD} = V_{M12} = V_{M3} = 5$ V, $V_{REF} = 1.65$ V, $SB = 3.3$ V, $R_L = 8$ $\Omega$ , $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Power supply current at standby	$I_{VMS}$	$SB = "L"$	—	—	10	$\mu\text{A}$
Control supply current at standby	$I_{SVS}$	$SB = "L"$ , $V_{REF} = 0$ V	—	—	10	$\mu\text{A}$
Control supply current at no input	$I_{SVA}$	$SB = "H"$	—	5	10	mA
Charge pump						
Output voltage	$V_{PMP}$	$I_{PMP} = 0$ mA	7.0	8.4	9.8	V
Current output capability	$V_{PMPL}$	$I_{PMP} = -1$ mA	5.9	7.3	8.7	V
Triangular wave generation circuit						
Sink current	$I_{CTSN}$	$V_{CT} = 1.6$ V	133	153	173	$\mu\text{A}$
Source current	$I_{CTSR}$	$V_{CT} = 0.1$ V	37	44	51	$\mu\text{A}$
Self-running oscillation frequency	$f_{TR}$	$C_{CT} = 100$ pF	175	200	225	kHz
Driver block						
Channel 1, 2 output on resistance (upper/lower)	$R_{ON1}$ , $R_{ON2}$	$R_L = 8$ $\Omega$	—	1.4	2.3	$\Omega$
Channel 3 output on resistance (upper/lower)	$R_{ON3}$	$R_L = 8$ $\Omega$	—	0.8	1.6	$\Omega$
Output offset voltage	$V_{OS}$	—	-50	—	50	mV
Voltage gain "+"	G	—	12.0	14.0	16.0	dB
"+" / "-" relative gain	$G_R$	—	-1.5	—	1.5	dB
Dead zone converted to input	$V_{DZ}$	—	0	10	30	mV
$V_{DD}$ reset						
Reset supply voltage	$V_{RESH}$	—	4.5	—	—	V
$V_{REF}$ reset						
High-level input voltage	$V_{RRH}$	—	1.35	—	—	V
Low-level input voltage	$V_{RRL}$	—	—	—	0.7	V
Standby operation						
High-level input voltage	$V_{SBH}$	—	2.7	—	—	V
Low-level input voltage	$V_{SBL}$	—	—	—	0.8	V

■ Electrical Characteristics at  $SV_{DD} = V_{M12} = V_{M3} = 5\text{ V}$ ,  $V_{REF} = 1.65\text{ V}$ ,  $SB = 3.3\text{ V}$ ,  $R_L = 8\ \Omega$ ,  $T_a = 25^\circ\text{C}$   
(continued)

• Design reference data

Note) The characteristics listed below are theoretical values based on the IC design and are not guaranteed.

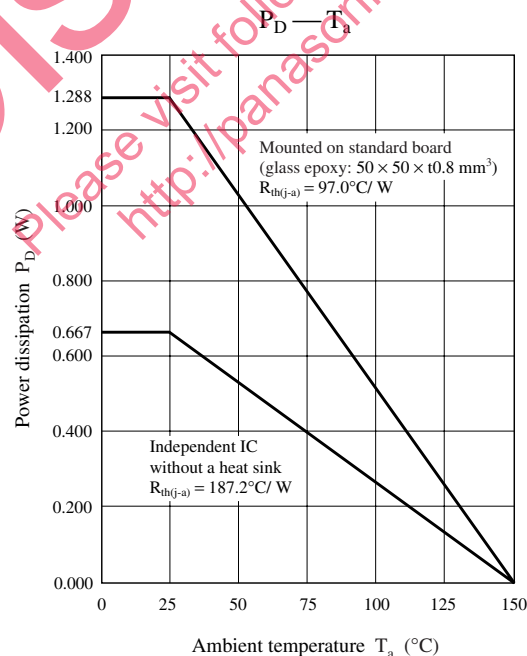
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Thermal protection						
Thermal protection operating temperature	$T_{TSD}$	—	—	160	—	$^\circ\text{C}$
Thermal protection hysteresis width	$\Delta T_{TSD}$	—	—	40	—	$^\circ\text{C}$
$SV_{DD}$ reset						
Hysteresis width	$\Delta V_{RES}$	—	—	0.2	—	V

■ Usage Notes

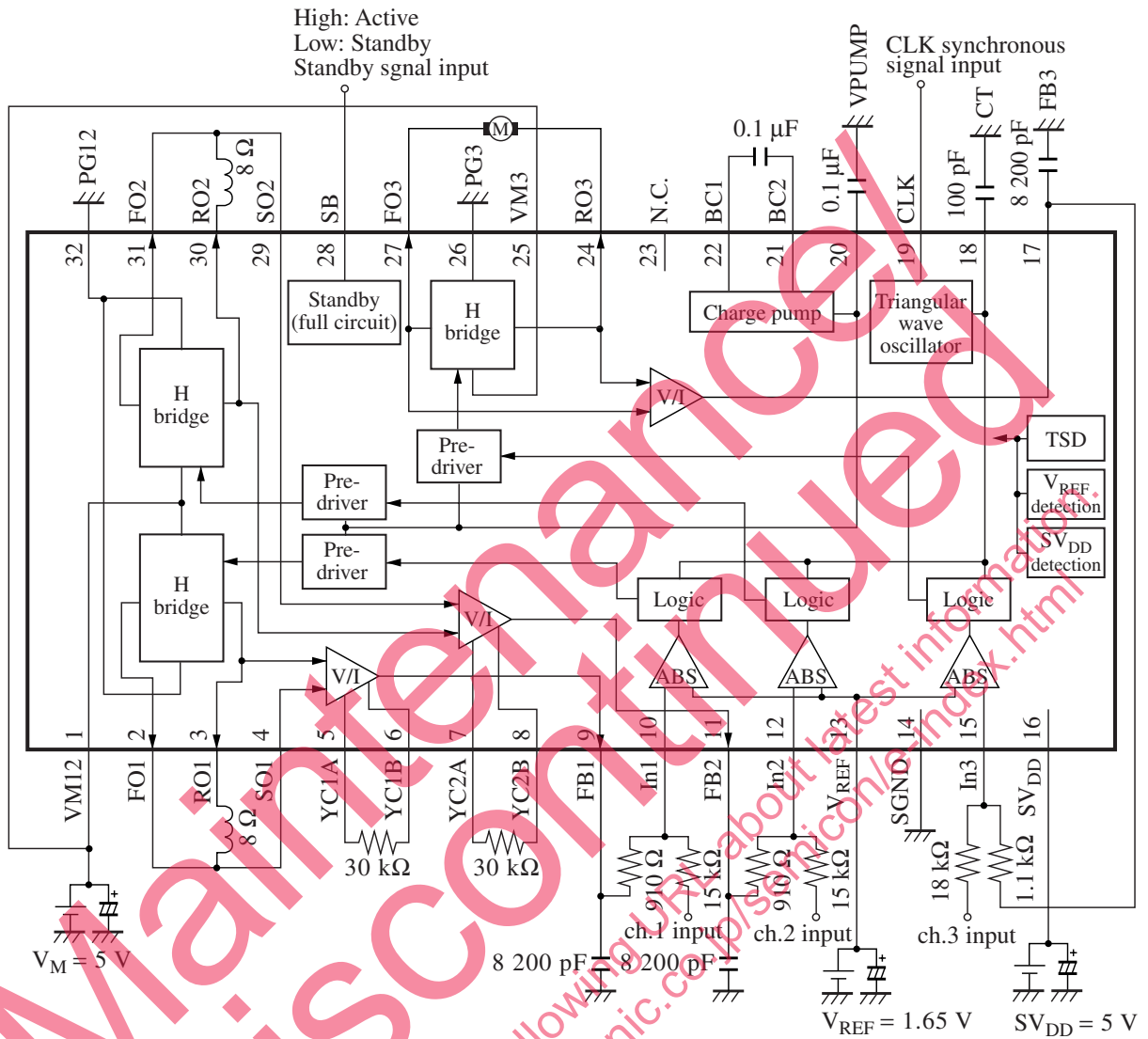
- Be sure to use  $SV_{DD}$  in the highest potential within the IC.
- Standby operation, reset operation  
Pin 28 is a standby switch input pin.  
You can get an active mode with high-level and standby mode with low-level. In a reset operation, all the functions of the IC stop. In a reset mode ( $SV_{DD}$  reset,  $V_{REF}$  reset and thermal protection on), only a charge pump operates.
- Power on and off be done in a standby mode ( $V_{SB}$ : Low).
- Do not use pin 13 ( $V_{REF}$ ) in an open state.
- Take time to check the characteristics on use.  
When changing an external circuit constant for use, consider not only static characteristics, but also transient characteristics and external parts with respect to the characteristics difference among ICs so that you can get enough margin.
- Keep each output pin from being short-circuited to  $SV_{DD}$  or VM or GND (line-to-supply and line-to-ground fault) and also between themselves (load short-circuit). Otherwise the IC will be damaged and is likely to get fired.
- Be cautious on a dip soldering. Prior study is required.

■ Application Note

- $P_D - T_a$  curves of SSOP032-P-0300

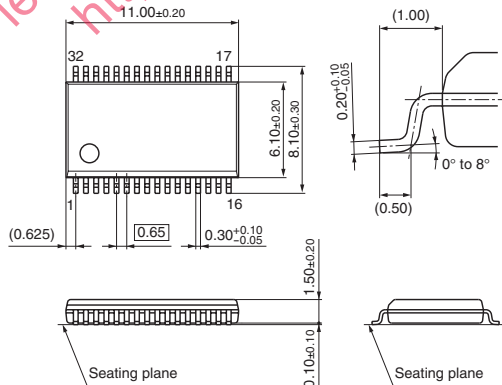


■ Application Circuit Example



■ New Package Dimensions (Unit: mm)

- SSOP032-P-0300B (Lead-free package)



## Request for your special attention and precautions in using the technical information and semiconductors described in this book

- (1) If any of the products or technical information described in this book is to be exported or provided to non-residents, the laws and regulations of the exporting country, especially, those with regard to security export control, must be observed.
- (2) The technical information described in this book is intended only to show the main characteristics and application circuit examples of the products, and no license is granted under any intellectual property right or other right owned by our company or any other company. Therefore, no responsibility is assumed by our company as to the infringement upon any such right owned by any other company which may arise as a result of the use of technical information described in this book.
- (3) The products described in this book are intended to be used for standard applications or general electronic equipment (such as office equipment, communications equipment, measuring instruments and household appliances).  
Consult our sales staff in advance for information on the following applications:
  - Special applications (such as for airplanes, aerospace, automobiles, traffic control equipment, combustion equipment, life support systems and safety devices) in which exceptional quality and reliability are required, or if the failure or malfunction of the products may directly jeopardize life or harm the human body.
  - Any applications other than the standard applications intended.
- (4) The products and product specifications described in this book are subject to change without notice for modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date Product Standards in advance to make sure that the latest specifications satisfy your requirements.
- (5) When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
  - Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- (6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.
- (7) This book may be not reprinted or reproduced whether wholly or partially, without the prior written permission of Matsushita Electric Industrial Co., Ltd.